ABSTRACT

SEMICONDUCTOR PACKAGE HAVING IMPLANTABLE CONDUCTIVE LANDS AND METHOD FOR MANUFACTURING THE

A semiconductor package having implantable conductive lands for simplifying the manufacture of the semiconductor package, reducing the manufacturing cost by reducing the price of raw materials and improving the electrical, thermal and mechanical performance of the semiconductor package, and a method for manufacturing the same are provided. The semiconductor package includes a semiconductor package body and implantable conductive lands fixed in the semiconductor package body and taken off a tape film serving as a substrate of the semiconductor package until a molding process is completed. The tape film that has served as the substrate is taken off and removed from the semiconductor package body after the molding process so that the semiconductor package body does not include a substrate therewithin.

FIG. 10